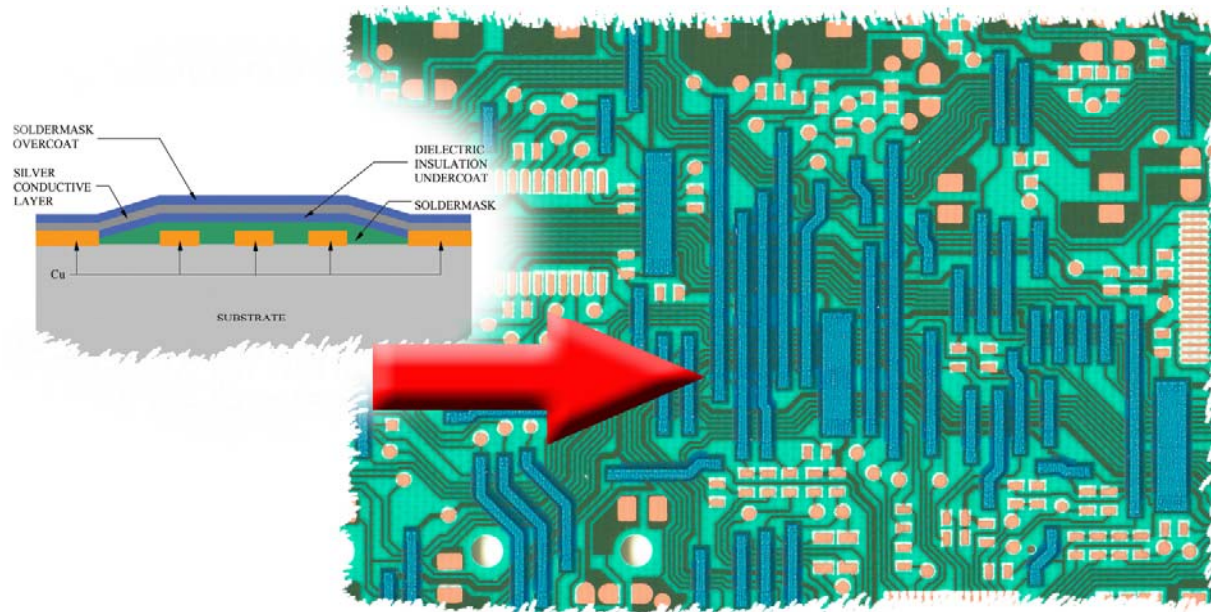
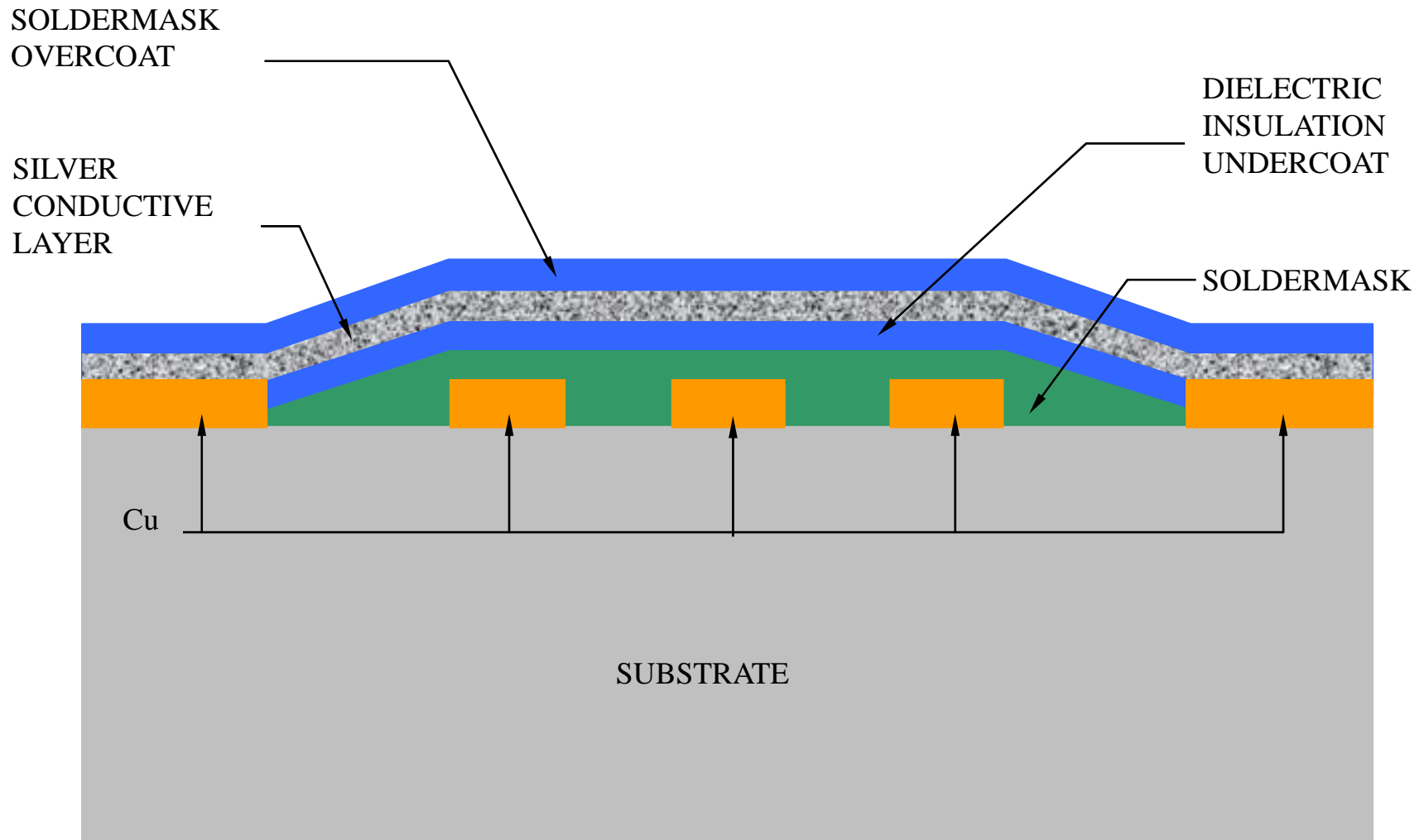
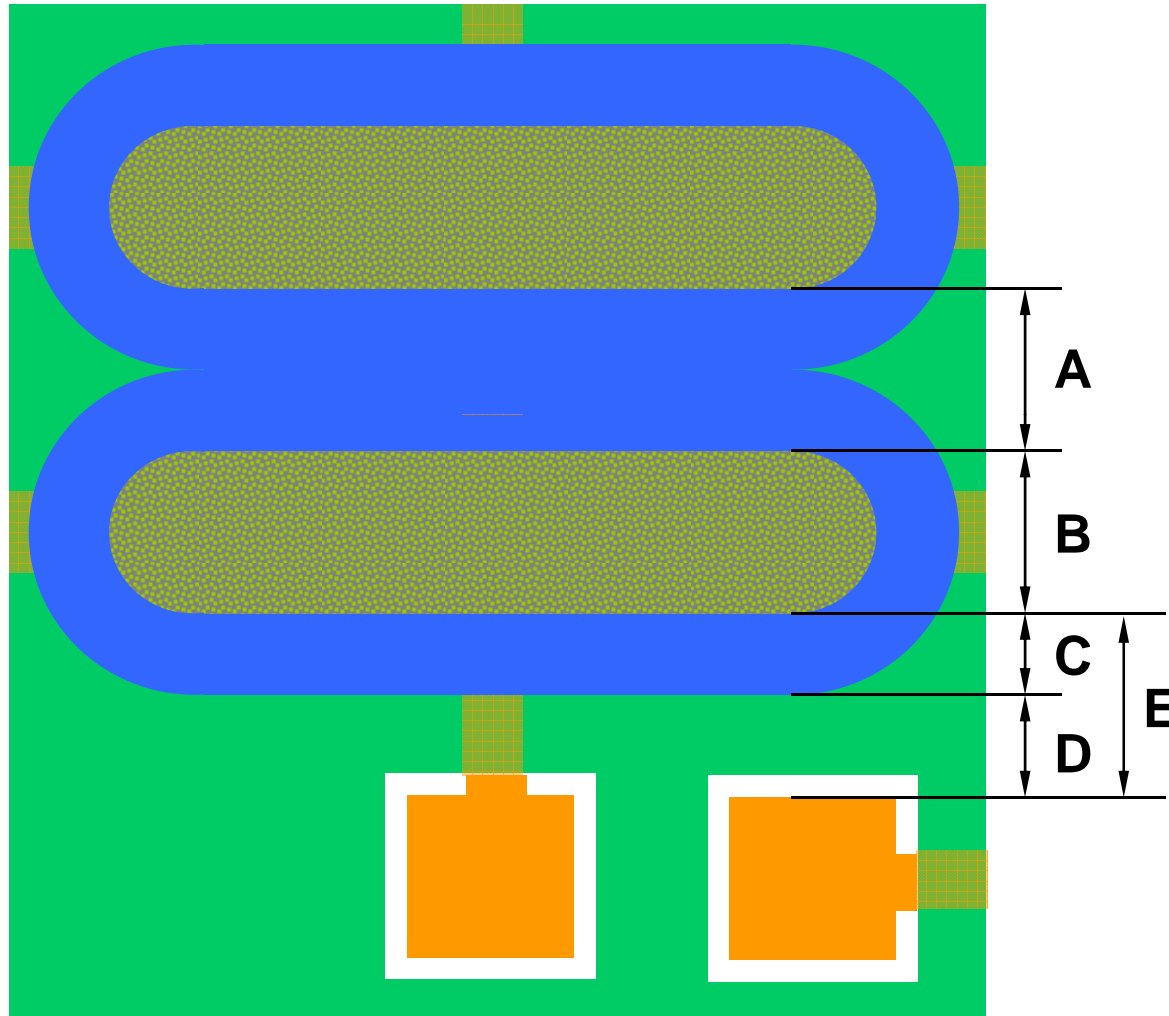


# GUIDE LINES FOR SILVER CROSS OVER PCB TECHNOLOGY

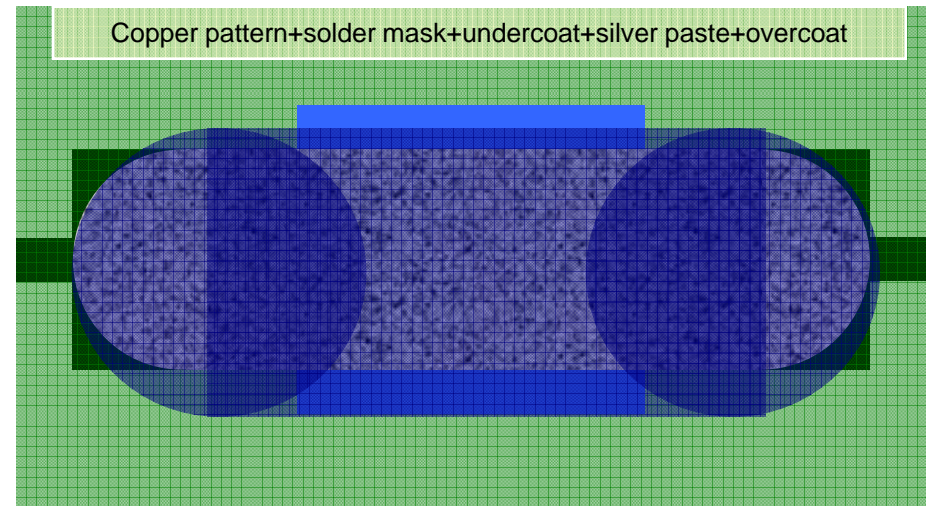
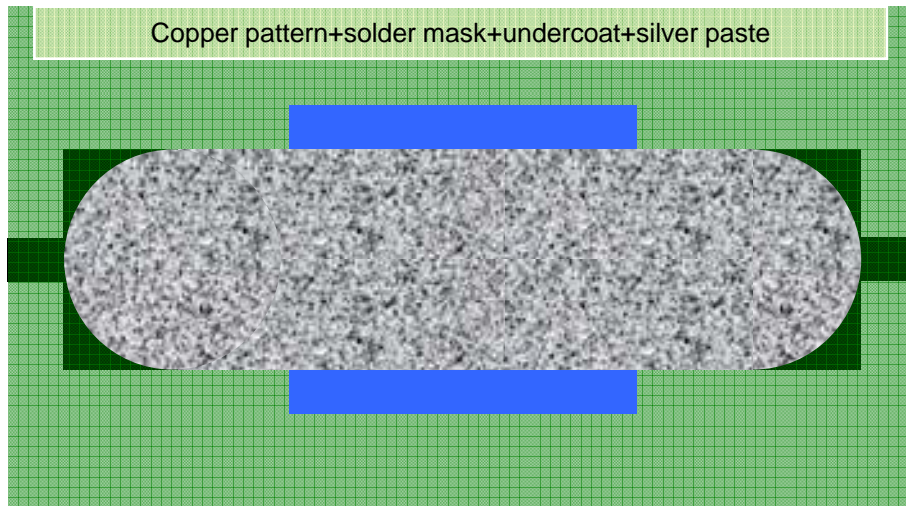
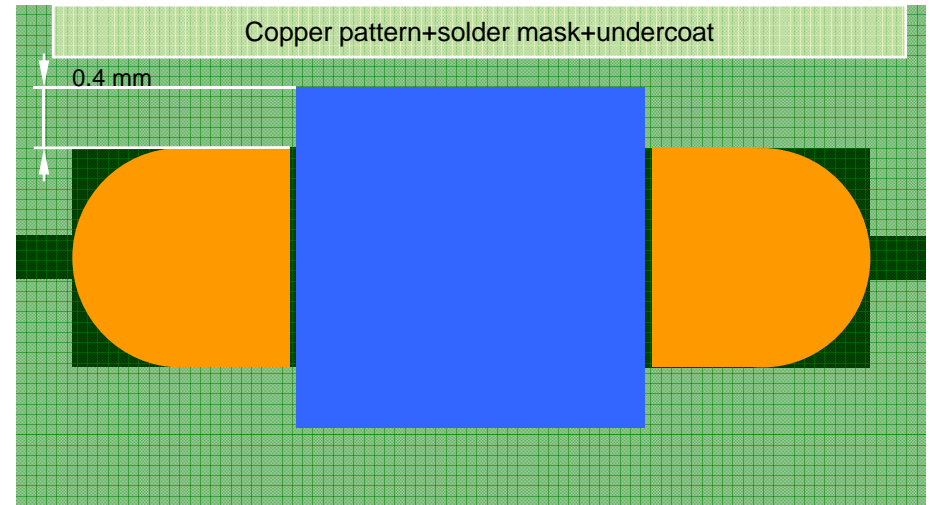
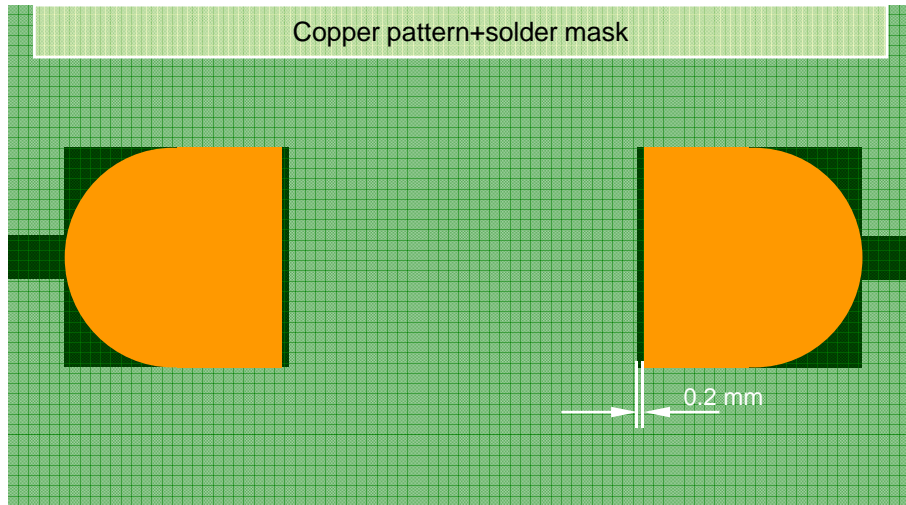


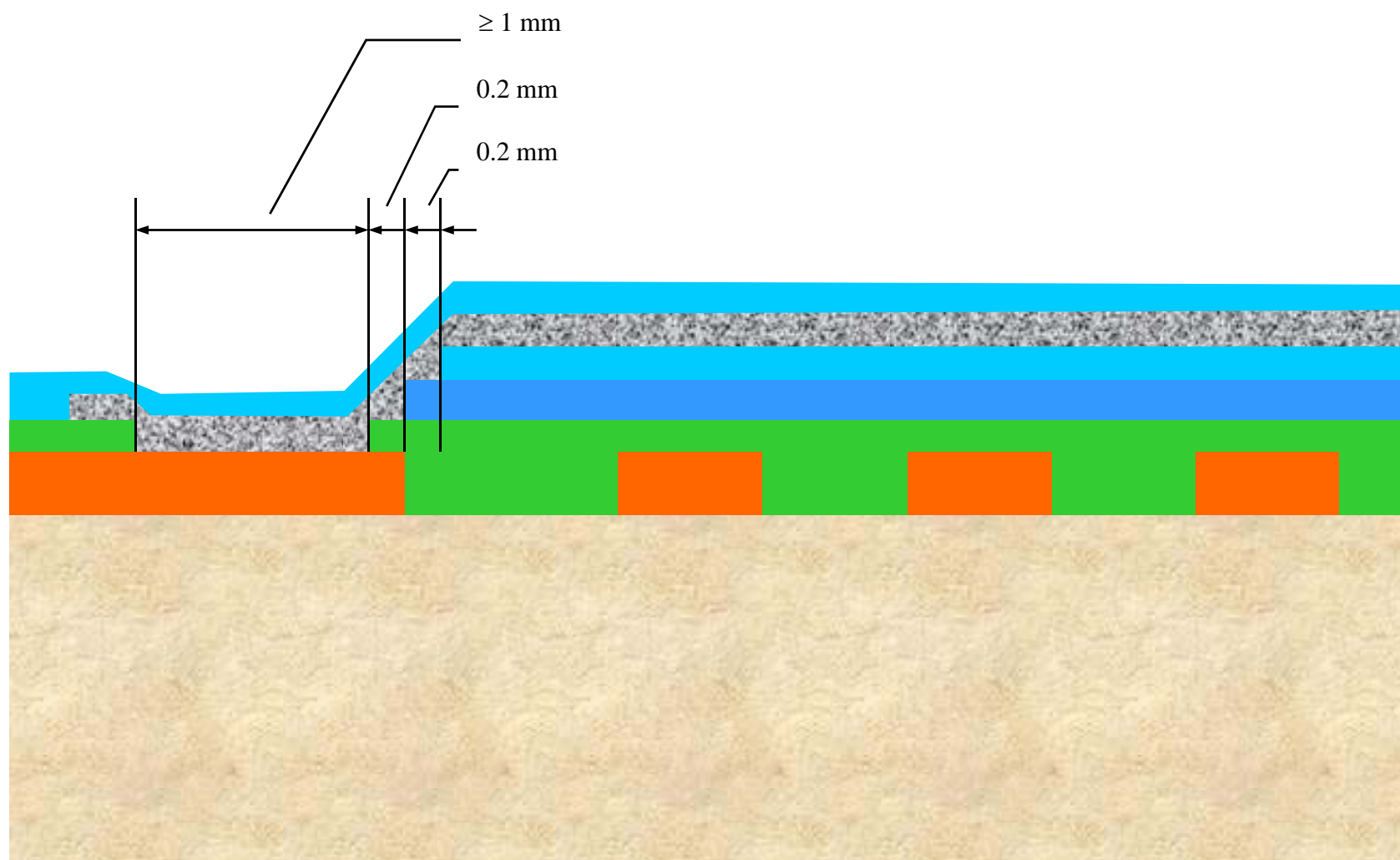
## TECHNICAL DESIGN RULES

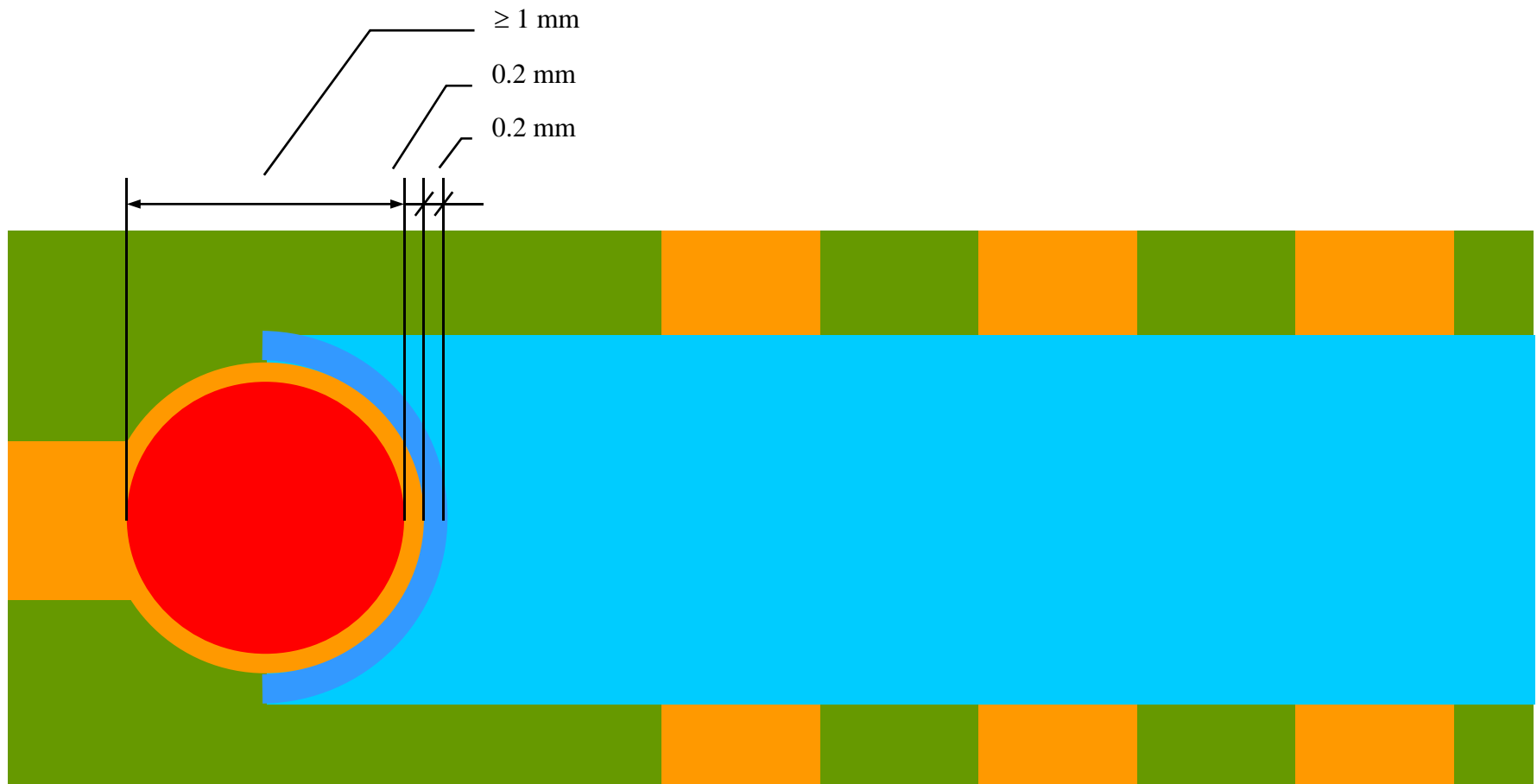


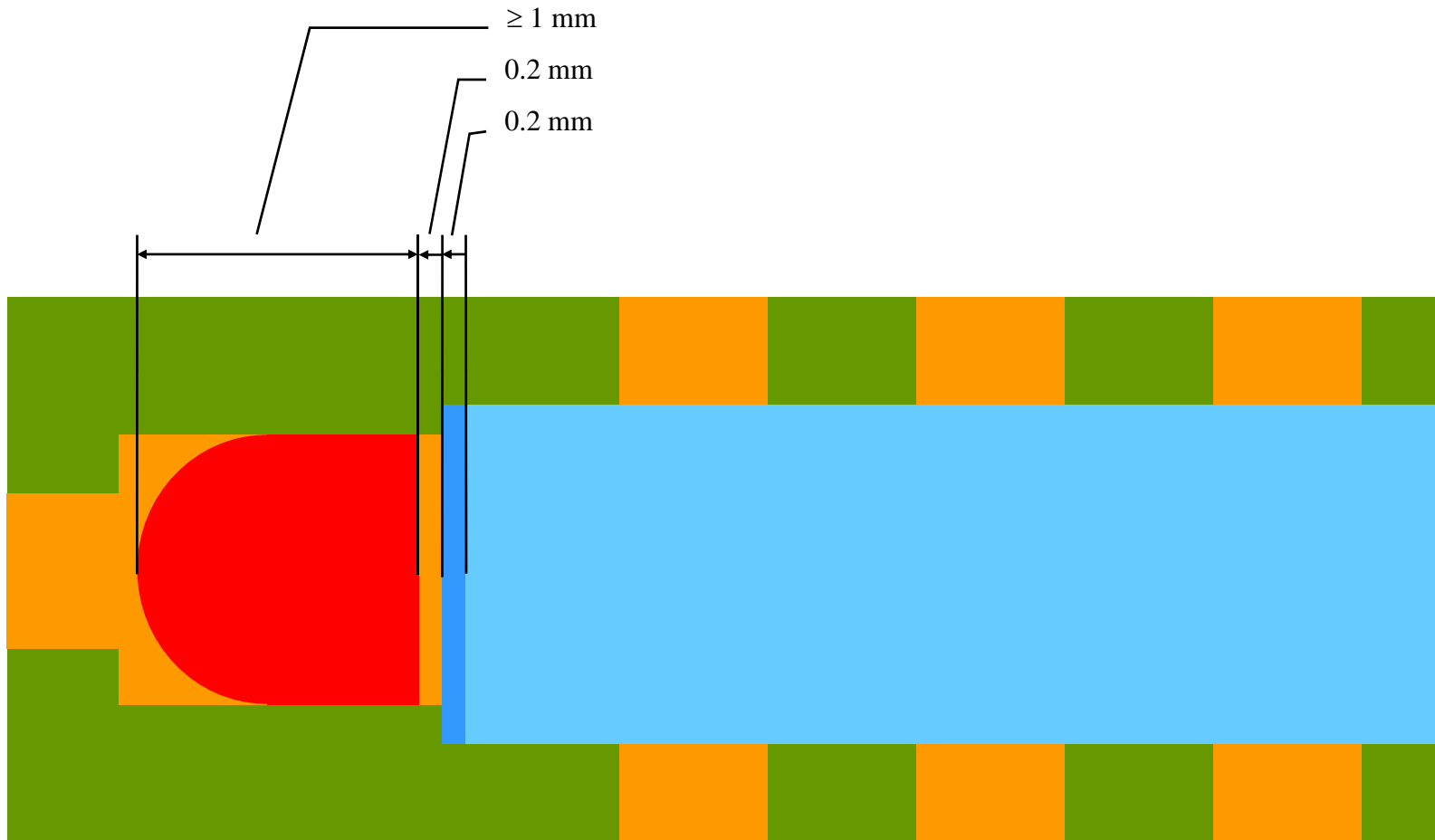


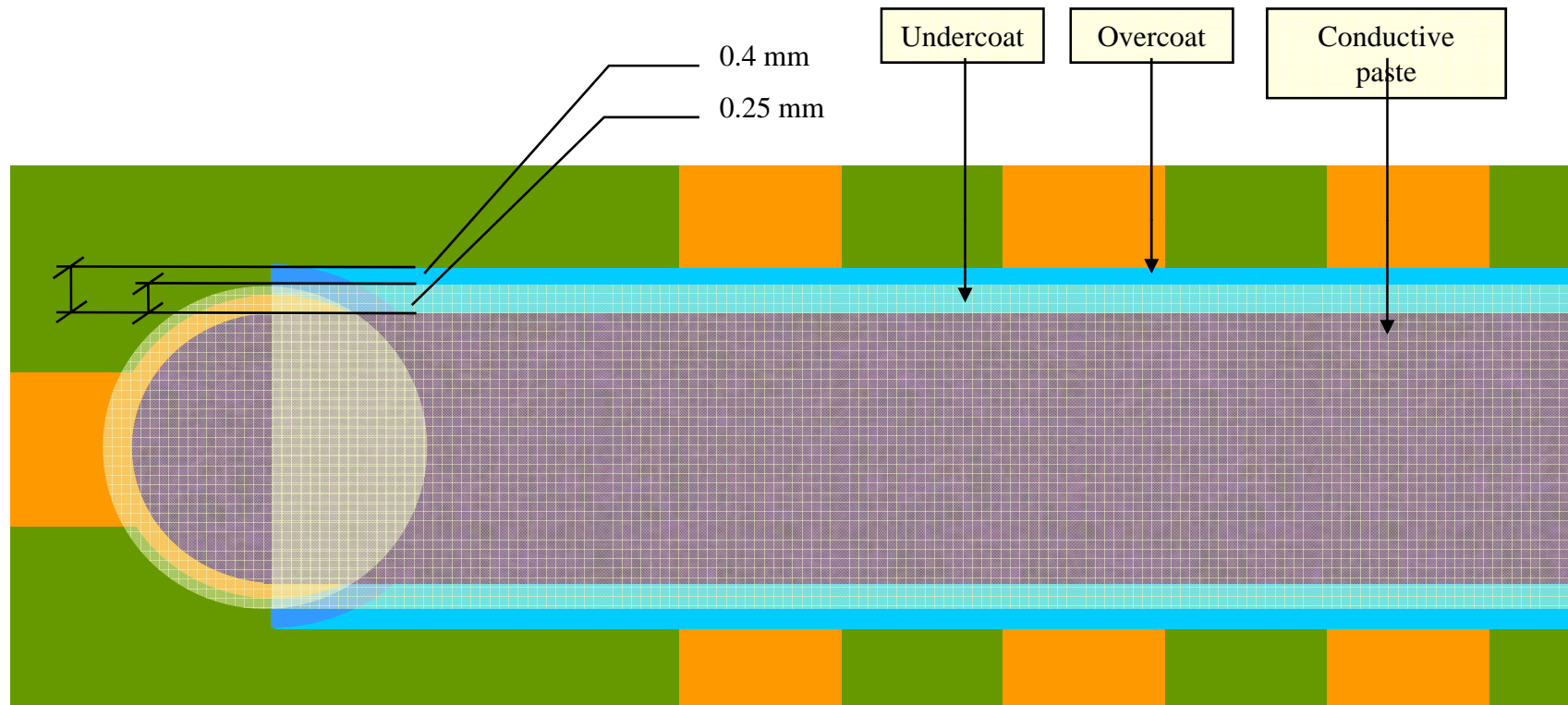
MINIMUM DIMENSIONS		
CODE	DESCRIPTION	DIMENSION (mm)
A	SCO ÷ SCO	0,7
B	WIDTH SCO	0,7
C	SCO ÷ UNDER COAT	0,4
D	UNDER COAT ÷ Cu	0,3
E	SCO ÷ Cu	0,7



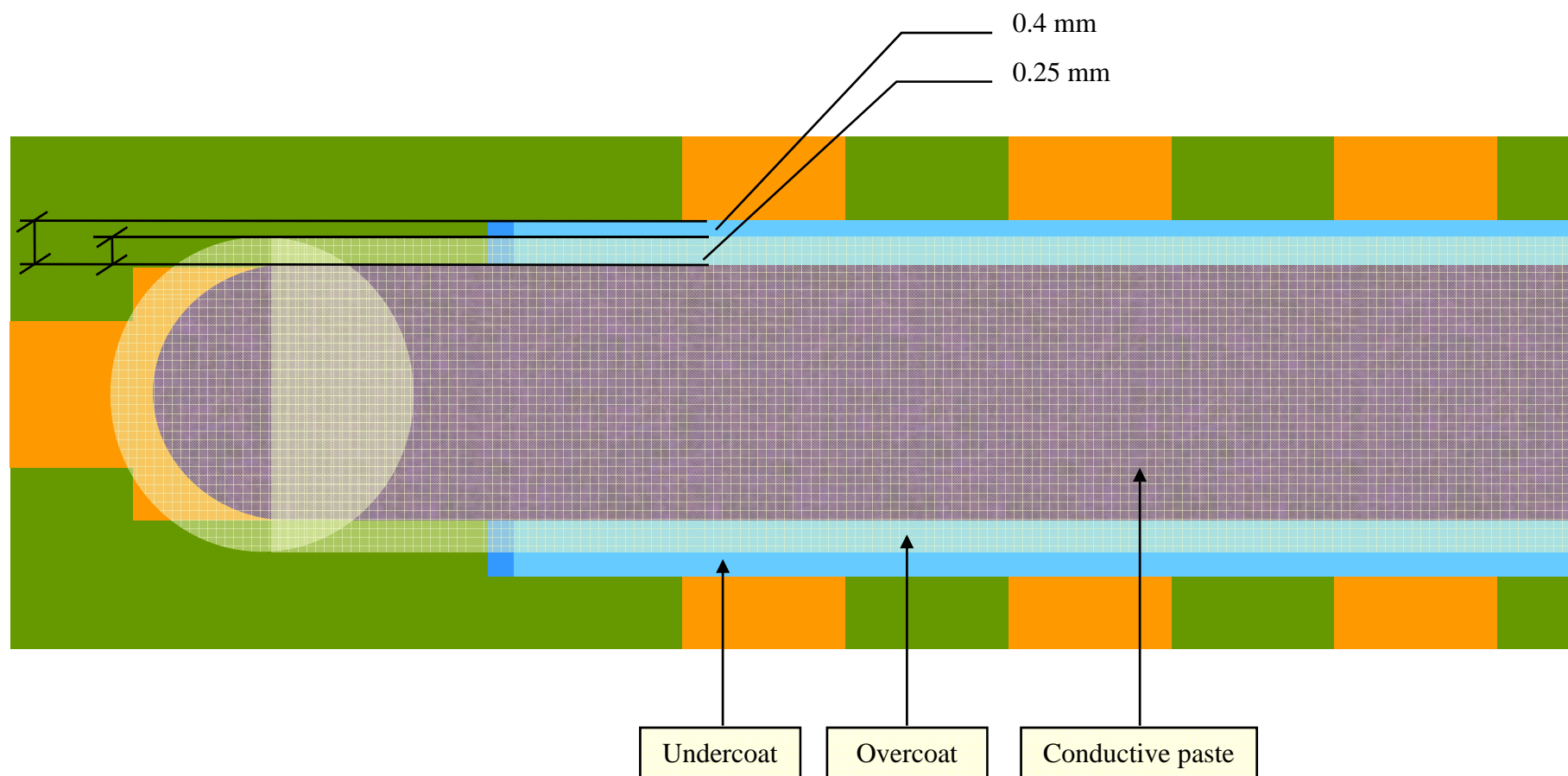


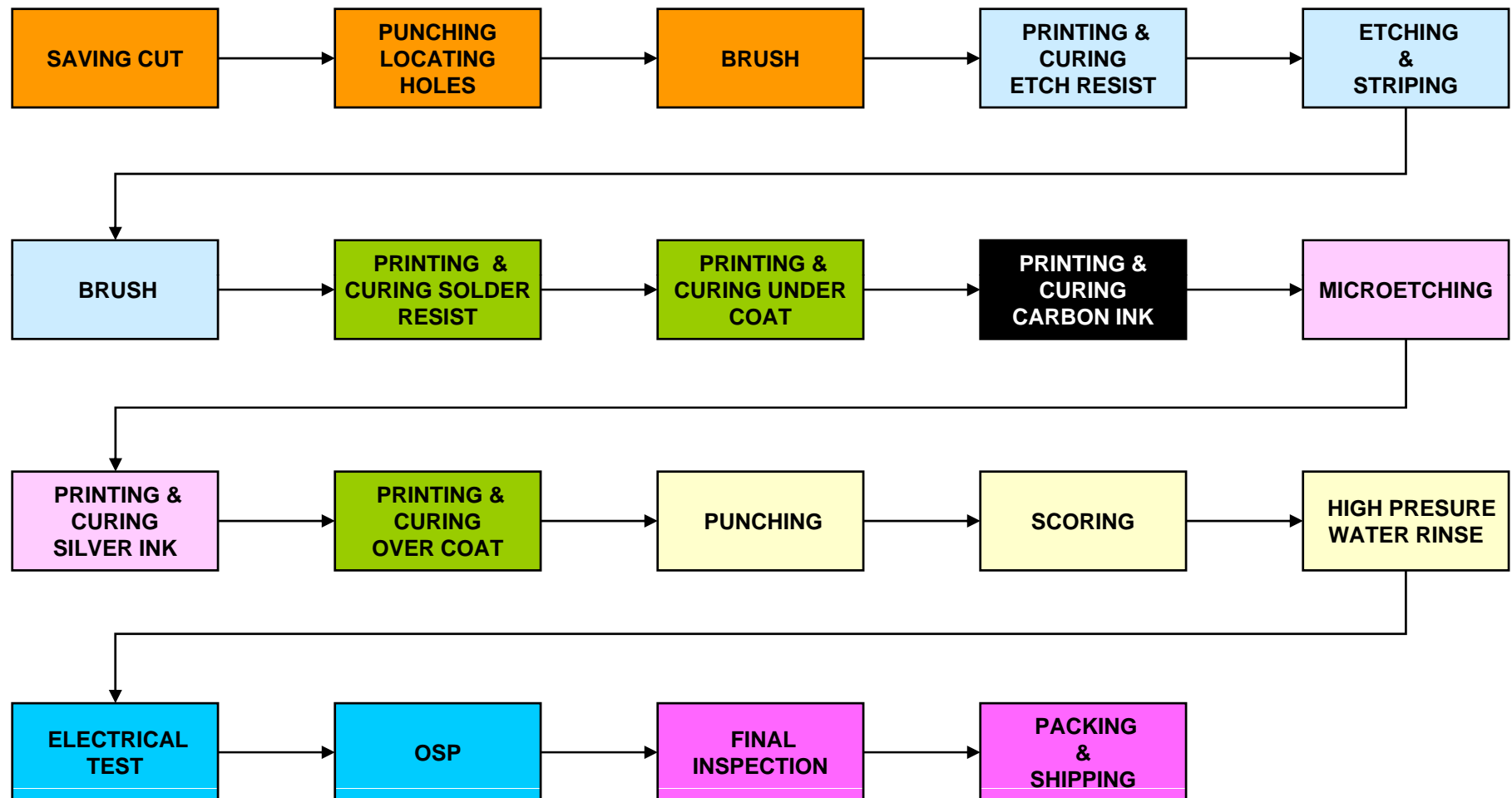












- **Raw material**
  - **ANSI grade**
    - FR-4, CEM-3, CEM-1, FR-3, FR-2, FR-1
  - **Thickness**
    - 1.2 ÷ 1.6 mm
  - **Copper thickness**
    - 35 µm
- **Lay out**
  - **Screen printing + UV curing**
- **Solder resist (under & over coat)**
  - **Screen printing + UV curing**
- **Silver paste**
  - **Screen printing + hot air oven**

- **Electrical**

- **Solder mask**

- **Thickness:**  $15 \pm 2 \mu\text{m}$
    - **Insulation resistance:**  $> 1\text{E}9 \Omega$
    - **Dielectric Breakdown:**  $> 650 \text{ VAC}$

- **Silver paste**

- **Thickness:**  $8 \div 20 \mu\text{m}$  (average =  $10 \mu\text{m}$ )
    - **Resistivity:**  $\leq 25 \text{ m}\Omega / \text{Square}$
    - **Current capacity:**  $A = 1 / (2 \times \Omega)$